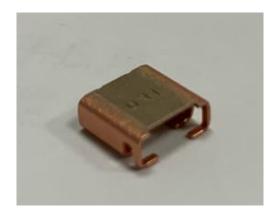


Leader New Energy Technology Co., Ltd.

# **High Power Shunt Resistor**





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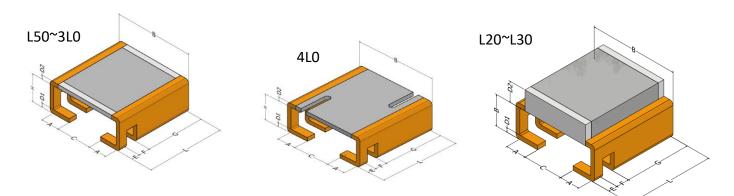
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#### Scope

This specification applies for metal type current shunt resistor.

#### Dimensions



Туре		Dimensions(mm)							
(inch size)	L	В	H(Ref)	E	F	А	D1	D2(ref)	
SR2725 L20	6.60±0.25	6.90±0.25	2.40	0.7±0.2	1.0±0.2	1.90±0.2	0.50±0.1	1.40	
SR2725 L30	6.60±0.25	6.90±0.25	2.40	0.7±0.2	1.0±0.2	1.90±0.2	0.50±0.1	1.40	
SR2725 L50	6.60±0.25	6.90±0.25	2.40	0.7±0.2	1.0±0.2	1.90±0.2	0.45±0.1	0.45	
SR2725 1L0	6.60±0.25	6.90±0.25	2.40	0.7±0.2	1.0±0.2	1.90±0.2	0.35±0.1	0.35	
SR2725 2L0	6.60±0.25	6.90±0.25	2.40	0.7±0.2	1.0±0.2	1.90±0.2	0.55±0.1	0.55	
SR2725 3L0/-L	6.60±0.25	6.90±0.25	2.40	0.7±0.2	1.0±0.2	1.90±0.2	0.35±0.1	0.35	
SR2725 4L0/-L	6.60±0.25	6.90±0.25	2.40	0.7±0.2	1.0±0.2	1.90±0.2	0.35±0.1	0.35	

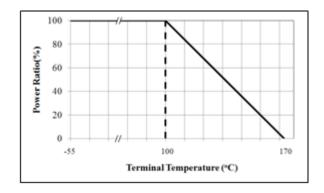
#### **Features**

- ◆ 5W permanent power, Inductance<3nH
- ♦ Internal heat resistance 15K/W
- Lead free, RoHs compliant for global applications and halogen free

#### Application

- Power modules
- Frequency converters
- Current sensor for power hybrid sources
- High current for automotive

#### **Derating Curve**



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#### **Part Numbers**

<u>SR</u>	<u>2725</u>	<u>E</u>	<u>F</u>	<u> </u>	<u>1L00</u>	<u>-L</u>

(1) (2) (3) (4) (5) (6)

(1)Series Name: SR (Shunt Resistor)

- (2) Chip size: 2725(inch)
- (3) Packaging Material: Emboss

(4)Resistance Tolerance:  $\pm 1\%$  (F),  $\pm 5\%$  (J)

(5)Power rating: I=5W, H=3W, E=2W

(6)Resistance Code: Ex: 1L0 means 1.0m  $\Omega,$  etc.

(7) L: means NiCrAl low inductance material

#### **Electrical Specification**

ltem	Power Rating	Resistance Operation Temp.   Power Rating Range(mΩ) Range		TCR (PPM/℃)	Resistance Material
SR2725	5W	0.2	<b>-55~+170</b> ℃	±50	MnCuSn
SR2725	5W	0.3	- <b>55~+170</b> ℃	±50	MnCu
SR2725	5W	0.5	- <b>55~+170</b> ℃	±50	MnCuSn
SR2725	5W	1.0	- <b>55~+170</b> ℃	±50	MnCu
SR2725	5W	2.0	- <b>55~+170</b> ℃	±50	FeCrAl
SR2725	3W	3.0	- <b>55~+170</b> ℃	±50	FeCrAl
SR2725-L	3W	3.0	- <b>55~+170</b> ℃	±50	NiCrAl
SR2725	2W	4.0~5.0	-55~+170℃	±50	FeCrAl
SR2725-L	2W	4.0~5.0	- <b>55~+170</b> ℃	±50	NiCrAl

#### Performances

#### **Environmental Performance**

No.	Item	Test Condition	Specification
1	Short Time Overload	Loading 5 times rate power 5sec	ΔR: ±1%
2	Temperature Coefficient of Resistance (T.C.R.)	-20°C /+125°C. (JIS-C5202-5.2) $TCR \text{ (ppm/°C)} = \frac{\Delta R}{R \times \Delta t} \times 10^{6}$	Refer to electrical specification.
3	Moisture Resistance	The specimens shall be placed in a chamber and subjected to a relative humidity of 90~98% percent and a temperature of 25°C / 65°C 10 cycles (MIL-STD-202, Method 106)	ΔR: ±1%



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4	High Temperature Exposure	The ship (mounted on board) is exposed in the heat chamber $170^{\circ}C$ for 1000 hrs. (JIS-C5202-7.2)	ΔR: ±1%
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#### Performances

#### **Environmental Performance**

No.	Item	Test Condition	Specification
5	Load Life	Apply rated power for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR: ±1%
6	Rapid change of temperature	The chip (mounted on board) is exposed, $-20\pm3^{\circ}$ C (30min.)/+125 $\pm2^{\circ}$ C (30min.) for 1000 cycles. The following conditions as the following figure. (JIS-C5202-7.4) Ambient temperature 30 min. 30 min. +125( $\pm2$ )'C 2~3min. -55( $\pm3$ )'C 2~3min.	ΔR: ±1%

#### Remark:

a. The terminal electron temperature of component should below 100°C.

#### **Function Performance**

No.	ltem	Test Condition	Specification		
2	Solderability	The specimen chip shall be immersed into the flux specified in the solder bath 235±5°C for 2±0.5 sec. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C5 202-6.11) Molten solder SMD h = 10  mm H = 10  mm min.	Solder shall be covered 95% or more of the electrode area.		

#### Remark:

All Reliability test should follow De-rating curve , terminal temperature of component should be below100°C.



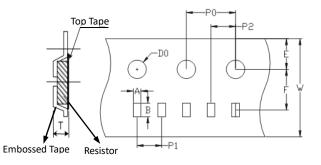
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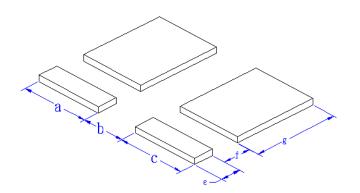
#### **Tape Packaging Specifications**

Embossed Plastic Tape Specifications



Туре		Carrier Dimensions (mm)								
Type	А	В	E	F	W	P0	P1	P2	D0	т
SR2725-L20 /L30	7.0±0.1	7.0±0.1	1.75±0.1	7.5±0.1	16.0±0.2	4.0±0.1	12.0±0.1	2.0±01	1.5±0.1	4.2 <u>±</u> 0.1
SR2725	7.0±0.1	7.0±0.1	1.75±0.1	7.5±0.1	16.0±0.2	4.0±0.1	12.0±0.1	2.0±01	1.5±0.1	3.1±0.1

#### **Recommended Pad Layout**



Туре	Dimensions(mm)					
(inch size)	а	b	С	е	f	g
SR2725	2.9	2	2.9	0.9	1	5.6

Note. pad size, solder insufficient, excessive solder, solder void and component shifted will affect the resistance accuracy

after IR reflow. Circuit calibration is a must to be done by functional test.

#### Packaging



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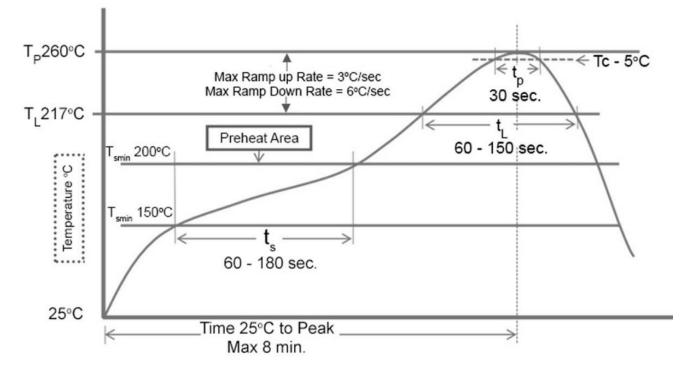
Size EIA (EIAJ)	2725
Standard Packing Quantity (pcs /Reel)	1400

#### **Storage Conditions**

Temperature : 22~28°C, Humidity : 40~75%

#### **Soldering Recommendations**

- Peak reflow temperatures and durations :
  - IR Reflow Peak =  $260^{\circ}$ C max for 10 sec
  - Not suitable for wave soldering
- Recommended IR Reflow Profile :



#### **ECN**

Engineering Change Notice : The customer will be informed with ECN if there is significant modification on the characteristics and materials described in Approval Sheet.